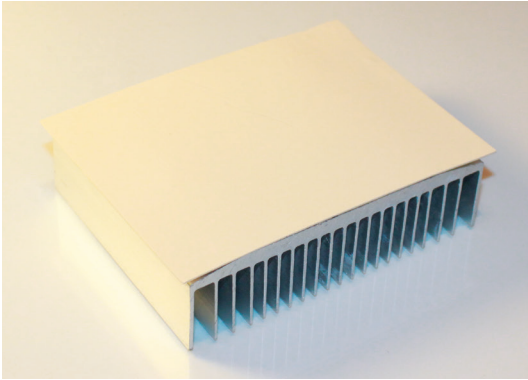


L37-3L

Low Bleed Thermal Pad



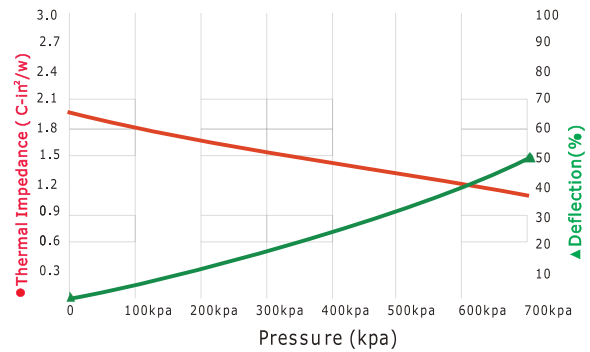
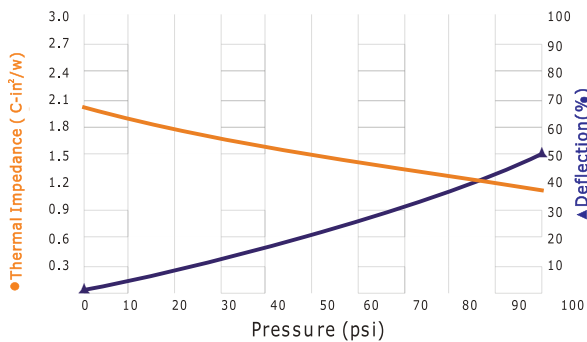
Features

- Low bleed
- High insulation strength
- Long term stability
- Low thermal resistance

Applications

- Electronic components: IC / CPU / MOS
- LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device / Wireless Hub etc...
- DDR II Module / DVD Applications / Hand-Set applications etc...

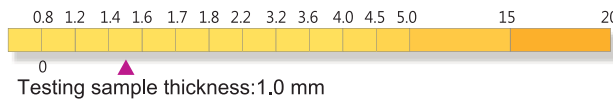
Thermal Resistance V.S Pressure V.S Deflection



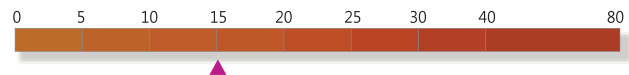
Properties

- REACH Compliant
- RoHS Compliant

Thermal Conductivity: 1.5 W/mK
(W/mK - Z Axis)



Hardness: 15 (Shore A)
(Shore A)



In the thermal resistance vs pressure vs deflection charts L37-3L provides low thermal impedance. As the pressure increases the thermal impedance decreases. L37-3L provides good compliance and softness.

Property	L37-3L	Unit	Test Method
Colour	Yellow	-	Visual
Thickness (Available thickness range)	0.5 - 10	mm	ASTM D374
	0.0197 - 0.3937	inch	ASTM D374
Optimal Temperature Range	-45 to 200	°C	-
Density	2.4	g/cm ³	ASTM D792
Thermal Conductivity	1.5	W/mK	ASTM D5470
Hardness	15	Shore A	ASTM D2240
Thermal Resistance			
T=1.0mm 10psi	2	K-in ² /W	ASTM D5470
T=1.0mm 50psi	1.5	K-in ² /W	ASTM D5470
T=1.0mm 100psi	1	K-in ² /W	ASTM D5470
Percent Deflection			
T=1.0mm 10psi	5	%	ASTM D575
T=1.0mm 50psi	20	%	ASTM D575
T=1.0mm 100psi	50	%	ASTM D575
Breakdown Voltage	15	kV/mm	ASTM D149
TML	<0.2	%	ASTM E595
Tensile Strength	1	Kgf/cm ²	ASTM D412
Elongation	300	%	ASTM D412

Available with an adhesive backing



L37-3L - $\frac{15}{1}$ - $\frac{20}{2}$ - $\frac{3}{2}$ - 0A, 20³

- Part Number
- Size X-Y-Z
- Quantity